ASSOCIATION CONNECTING ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® international and	<b>nposition De</b> 5. IPC, Bannockl Pan-American c	ourn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	vithin the manufactu level materials for w	rer listed i which the n	em. Note: i nanufacture	f the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ   http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information			
upplier Information														
Company name* Company			pany unique ID			Unique ID Authority				Respons	Response Date*			
onsemi										2025-06	2025-06-08			
Contact Name Title - Conta			tact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			resentative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product En			uct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	Mfr Item Number		Mfr Item Name		Effective Date	Version Manufacturing Site		Ianufacturing Site		Weight*	UOM	Unit Type	
	FDT457	N	30V SOT-223 NCH			2025-06-08		М	MY1		118.648	mg	Each	
Ianufacturing Proccess Infor	nation					•								
Terminal Plating / Grid Array	ating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Peal		Temperature Number of Reflow Cycles						
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260	C 30		seconds 3					
omments														
vel 1 - maximum time at peak tempe	rature during so	ldering is 10-3	0 seconds											
or more information regarding mate	rial composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.54	mg	Supplier	Silicon (Si)	7440-21-3		1.54	mg
Die Attach Solder	0.541	mg	Supplier	Silver (Ag)	7440-22-4		0.0135	mg
			А	Lead (Pb)	7439-92-1	7a	0.5004	mg
			Supplier	Tin (Sn)	7440-31-5		0.027	mg
Lead Frame	66.944	mg	Supplier	Silver (Ag)	7440-22-4		0.234	mg
			Supplier	Zinc (Zn)	7440-66-6		0.08	mg
			Supplier	Iron (Fe)	7439-89-6		1.61	mg
			Supplier	Copper (Cu)	7440-50-8		65	mg
			Supplier	Phosphorus (P)	7723-14-0		0.02	mg
Mold Compound-Black	41.108	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		0.4111	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.1662	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.0277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30.0088	mg
			Supplier	Silica (SiO2)	14464-46-1		0.2055	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.0831	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2055	mg
Plating	8.29	mg	Supplier	Tin (Sn)	7440-31-5		8.29	mg
Wire Bond - Cu	0.225	mg	Supplier	Copper (Cu)	7440-50-8		0.225	mg